

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT6862881

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SIK LUI	08/05/2021
MADHUR BOBDE	08/12/2021
LINGPENG GUAN	08/06/2021
LEI ZHANG	08/06/2021
RECEIVING PARTY DATA	
Name:	ALPHA AND OMEGA SEMICONDUCTOR INTERNATIONAL LP
Street Address:	100 KING STREET WEST, SUITE # 6000
City:	TORONTO
State/Country:	CANADA
Postal Code:	M5X 1E2
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17401183
CORRESPONDENCE DATA	
Fax Number:	(510)668-0239
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	5106680965
Email:	josh@jdipatent.com
Correspondent Name:	JOSHUA D. ISENBERG
Address Line 1:	809 CORPORATE WAY
Address Line 4:	FREMONT, CALIFORNIA 94539
ATTORNEY DOCKET NUMBER:	ANO-108/US
NAME OF SUBMITTER:	JOSHUA D. ISENBERG
SIGNATURE:	/Joshua D. Isenberg, Reg. No. 41088/
DATE SIGNED:	08/12/2021
Total Attachments: 4	
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ASSIGNMENT

INVENTOR AND CITY Whereas, I, **Sik Lui** residing at **Sunnyvale, California, USA**

have invented:

TITLE: **BOTTOM SOURCE TRENCH MOSFET WITH SHIELD ELECTRODE**

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on Aug 5, 2021, Said assignor hereby authorize and request their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 17/401,183, filed August 12, 2021) the filing date and application number of said application when known.

Whereas, **Alpha and Omega Semiconductor International LP**, a Canadian Corporation, having its registered address at 100 King Street West, Suite # 6000, Toronto, Canada M5X 1E2, (hereinafter called **AOS**), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **AOS**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to **AOS** its successors and assigns; and I hereby agree that **AOS** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND Signed and Sealed at _____

DATE on Aug. 5, 2021



Sik Lui

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **Madhur Bobde** residing at **Sunnyvale, California, USA**

have invented:

TITLE: **BOTTOM SOURCE TRENCH MOSFET WITH SHIELD ELECTRODE**

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on _____, 2021, Said assignor hereby authorize and request

their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 17/401,183, filed August 12, 2021) the filing date and application number of said application when known.

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CITY AND Signed and Sealed at Sunnyvale CA

DATE on August 12th, 2021

Madhur Bobde

Madhur Bobde

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **Lingpeng Guan** residing at **San Jose, California, USA**

have invented:

TITLE: **BOTTOM SOURCE TRENCH MOSFET WITH SHIELD ELECTRODE**

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on Aug 06, 2021, Said assignor hereby authorize and request

their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 17/401,183, filed August 12, 2021) the filing date and application number of said application when known.

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CITY AND Signed and Sealed at Sunnyvale

DATE on Aug. 06, 2021

Lingpeng Guan
Lingpeng Guan

ASSIGNMENT

INVENTOR AND CITY Whereas, I, **Lei Zhang** residing at **Portland, Oregon, USA**

have invented:

TITLE: **BOTTOM SOURCE TRENCH MOSFET WITH SHIELD ELECTRODE**

DATE INVENTOR SIGNED THE DECLARATION and executed a United States patent application therefor on Aug-6th, 2021, Said assignor hereby authorize and request

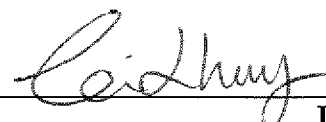
their attorney, Joshua D. Isenberg, of 809 Corporate Way, Fremont, California, to insert here in parentheses (Application number 17/401,183, filed August 12, 2021) the filing date and application number of said application when known.

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CITY AND Signed and Sealed at Portland, Oregon

DATE on Aug-6th, 2021



Lei Zhang